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专业PCB打样工厂SN54时01845SN74HC174 HEX D-TYPE FLIP-FLOPS WITH CLEAR SCLS119B - DECEMBER 1982 - REVISED MAY 1997

- **Contain Six Flip-Flops With Single-Rail** Outputs
- **Applications Include:**
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators
- **Package Options Include Plastic** Small-Outline (D) and Ceramic Flat (W) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

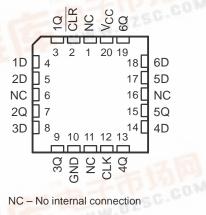
These monolithic positive-edge-triggered D-type flip-flops have a direct clear (\overline{CLR}) input.

Information at the data (D) inputs meeting the setup time requirements is transferred to the outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going edge of CLK. When CLK is at either the high or low level, the D input has no effect at the output.

The SN54HC174 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74HC174 is characterized for operation from -40°C to 85°C.

CLR 1 16 V _{CC}	GE
1Q 2 15 6Q	GE
1D 3 14 6D 2D 4 13 5D 2Q 5 12 5Q 3D 6 11 4D 3Q 7 10 4Q GND 8 9 CLK	

SN54HC174 . . . FK PACKAGE (TOP VIEW)



	FUNCTION TABLE (each flip-flop)											
		INPUTS		OUTPUT								
5	CLR	CLK	D	Q								
	L	Х	Х	L								
	Н	\uparrow	Н	н								
	н	\uparrow	L	L								
	Н	L	Х	Q ₀								

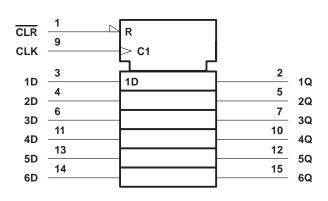
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SN54HC174, SN74HC174 HEX D-TYPE FLIP-FLOPS WITH CLEAR

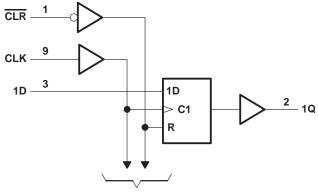
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logic symbol[†]



 † This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, N, and W packages.

logic diagram (positive logic)



To Five Other Channels

Pin numbers shown are for the D, J, N, and W packages.

absolute maximum ratings over operating free-air temperature range[‡]

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, $I_O (V_O = 0 \text{ to } V_{CC})$	±25 mA
Continuous current through V _{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	113°C/W
N package	
Storage temperature range, T _{stg}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51, except for through-hole packages, which use a trace length of zero.



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			SI	SN54HC174			SN74HC174		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		2	5	6	2	5	6	V
		$V_{CC} = 2 V$	1.5			1.5			
VIH High-level input voltage	High-level input voltage	$V_{CC} = 4.5 V$	3.15			3.15			V
		ACC = 6 A	4.2			4.2			
VIL		$V_{CC} = 2 V$	0		0.5	0		0.5	
	Low-level input voltage	$V_{CC} = 4.5 V$	0		1.35	0		1.35	V
		VCC = 6 V	0		1.8	0		1.8	
VI	Input voltage		0		VCC	0		VCC	V
VO	Output voltage		0		VCC	0		VCC	V
		$V_{CC} = 2 V$	0		1000	0		1000	
tt	Input transition (rise and fall) time	$V_{CC} = 4.5 V$	0		500	0		500	ns
		VCC = 6 V	0		400	0		400	
TA	Operating free-air temperature		-55		125	-40		85	°C

recommended operating conditions

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	PARAMETER TEST CONDITIONS		Vaa	Т	A = 25°C	;	SN54H	IC174	SN74H	C174	UNIT	
PARAMETER	TEST CC	NDITIONS V _{CC}		MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V	1.9	1.998		1.9		1.9			
		I _{OH} = –20 μA	4.5 V	4.4	4.499		4.4		4.4			
VOH	$V_I = V_{IH} \text{ or } V_{IL}$		6 V	5.9	5.999		5.9		5.9		V	
		I _{OH} = -4 mA I _{OH} = -5.2 mA	4.5 V	3.98	4.3		3.7		3.84			
			6 V	5.48	5.8		5.2		5.34			
			2 V		0.002	0.1		0.1		0.1		
		I _{OL} = 20 μA	4.5 V		0.001	0.1		0.1		0.1		
VOL	$V_I = V_{IH} \text{ or } V_{IL}$	$V_I = V_{IH} \text{ or } V_{IL}$		6 V		0.001	0.1		0.1		0.1	V
		$I_{OL} = 4 \text{ mA}$ $I_{OL} = 5.2 \text{ mA}$	4.5 V		0.17	0.26		0.4		0.33		
			6 V		0.15	0.26		0.4		0.33		
li li	$V_I = V_{CC} \text{ or } 0$		6 V		±0.1	±100		±1000		±1000	nA	
ICC	$V_I = V_{CC} \text{ or } 0,$	IO = 0	6 V			8		160		80	μΑ	
Ci			2 V to 6 V		3	10		10		10	pF	



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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

			Nee	T _A =	25°C	SN54H	IC174	SN74F	IC174	UNIT	
			Vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT	
			2 V	0	6	0	4.2	0	5		
fclock	f _{clock} Clock frequency		4.5 V	0	31	0	21	0	25	MHz	
			6 V	0	36	0	25	0	29		
		2 V	80		120		100				
		CLR low	4.5 V	16		24		20			
	Pulse duration		6 V	14		20		17		ns	
۱W	w the second sec		2 V	80		120		100			
		CLK high or low	4.5 V	16		24		20			
			6 V	14		20		17			
			2 V	100		150		125			
		Data	Data	4.5 V	20		30		25		
	Setup time before CLK1		6 V	17		25		21		20	
t _{su}	Setup time before CERT		2 V	100		150		125		ns	
		CLR inactive	CLR inactive	4.5 V	20		30		25		
			6 V	17		25		21			
			2 V	0		0		0			
t _h Hold time, data after CLK↑			4.5 V	0		0		0		ns	
			6 V	0		0		0			

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

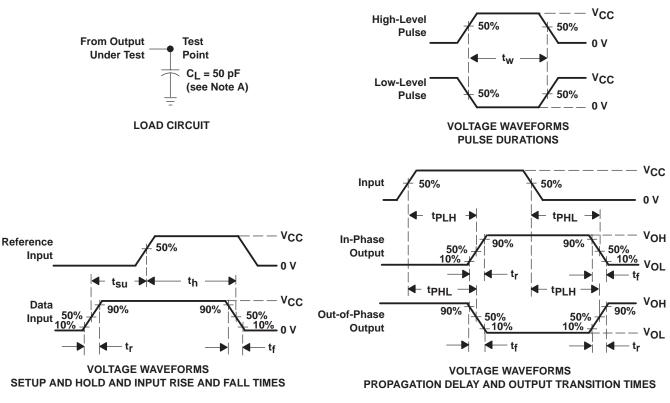
PARAMETER	FROM	то	Vaa	Τ,	λ = 25°C	;	SN54H	C174	SN74H	IC174	UNIT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	9		4.2		5		
f _{max}			4.5 V	31	44		21		25		MHz
			6 V	36	50		25		29		
	CLR	Any	2 V		58	160		240		200	
			4.5 V		17	32		48		40	40 34 200 40
. .			6 V		14	27		41		34	
^t pd		Any	2 V		58	160		240		200	
	CLK		4.5 V		17	32		48		40	
			6 V		14	27		41		34	
			2 V		38	75		110		90	
t _t		Any	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance per flip-flop	No load	27	pF



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_Q = 50 Ω , t_f = 6 ns, t_f = 6 ns.
- C. For clock inputs, f_{max} is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



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